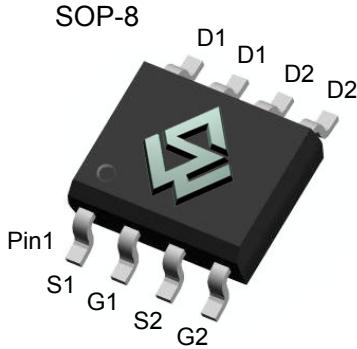
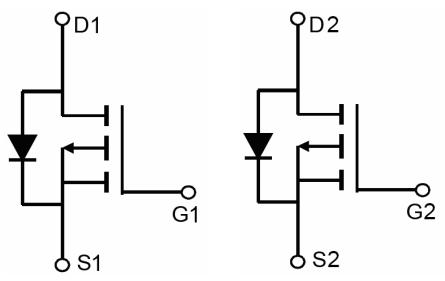


## 30V Dual P-Channel Enhancement-Mode MOSFET

General Description	Product Summary		
• Low gate charge.	• $BV_{DSS}$	-30V	
• Use as a load switch.	• $R_{DS(on)}$ @ $V_{GS} = 10V$	< 60mΩ	
• Use in PWM applications	• $R_{DS(on)}$ @ $V_{GS} = 4.5V$	< 90mΩ	

	
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Absolute Maximum Ratings ( $T_A = 25^\circ C$ unless otherwise noted)				
Parameter	Symbol	Maximum	Units	
Drain-Source Voltage	$V_{DS}$	-30	V	
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V	
Drain Current ( $T_A=25^\circ C$ )	$I_D$	-5.3	A	
Drain Current ( $T_A=75^\circ C$ )		-2.8	A	
Pulsed Drain Current <sup>a</sup>	$I_{DM}$	-18	A	
Power Dissipation <sup>b</sup> ( $T_A=25^\circ C$ )	$P_D$	2.5	W	
Power Dissipation <sup>b</sup> ( $T_A=75^\circ C$ )		1.0	W	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 ~ +150	°C	

Thermal Characteristics				
Parameter	Symbol	Maximum	Units	
Junction-to-Ambient <sup>a</sup> ( $t \leq 10s$ )	$R_{\theta JA}$	50	°C/W	
Junction-to-Ambient <sup>a,d</sup> (Steady-State)		90	°C/W	
Junction-to-Lead (Steady-State)	$R_{\theta JL}$	25	°C/W	

<b>Electrical Characteristics</b> ( $T_A = 25^\circ\text{C}$ unless otherwise noted)						
<b>Symbol</b>	<b>Parameter</b>	<b>Conditions</b>	<b>Min</b>	<b>Typ</b>	<b>Max</b>	<b>Units</b>
<b>Off Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0\text{V}$ , $I_D = -250\mu\text{A}$	-30			V
$\text{I}_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}} = -24\text{V}$ , $V_{\text{GS}} = 0\text{V}$			-1	$\mu\text{A}$
$\text{I}_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{GS}} = \pm 20\text{V}$ , $V_{\text{DS}} = 0\text{V}$			$\pm 100$	nA
<b>On Characteristics</b>						
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}$ , $I_D = -250\mu\text{A}$	-1		-2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance	$V_{\text{GS}} = -10\text{V}$ , $I_D = -5.3\text{A}$			60	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}$ , $I_D = -4.5\text{A}$			90	$\text{m}\Omega$
$\text{g}_{\text{FS}}$	Forward Transconductance	$V_{\text{DS}} = -10\text{V}$ , $I_D = -5.3\text{A}$		18		S
<b>Drain-Source Diode Characteristics</b>						
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}} = 0\text{V}$ , $I_S = -1.0\text{A}$			-1.3	V
$I_S$	Maximum Body-Diode Continuous Current				-2.0	A
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}} = -15\text{V}$ , $V_{\text{GS}} = 0\text{V}$ $f = 1.0\text{MHz}$		553		pF
$C_{\text{oss}}$	Output Capacitance			93		pF
$C_{\text{rss}}$	Reverse Transfer Capacitance			63		pF
<b>Switching Characteristics</b>						
$Q_g$	Total Gate Charge	$V_{\text{DS}} = -15\text{V}$ , $I_D = -5.3\text{A}$ $V_{\text{GS}} = -10\text{V}$		12		nC
$Q_{\text{gs}}$	Gate-Source Charge			4		nC
$Q_{\text{gd}}$	Gate-Drain Charge			5		nC
$t_{\text{D}(\text{ON})}$	Turn-On Delay Time	$V_{\text{DD}} = -15\text{V}$ , $I_D = -1\text{A}$ $V_{\text{GS}} = -10\text{V}$ $R_{\text{GEN}} = -6 \text{ ohm}$		14		ns
$t_r$	Turn-On Rise Time			5		ns
$t_{\text{D}(\text{OFF})}$	Turn-Off Delay Time			20		ns
$t_f$	Turn-Off Fall Time			6		ns

- a. Repetitive rating, Pulse width limited by junction temperature  $T_{J(\text{MAX})}=150^\circ\text{C}$ . Ratings are based on low frequency and duty cycles to keep initial  $T_J=25^\circ\text{C}$
- b. The power dissipation  $P_D$  is based on  $T_{J(\text{MAX})}=150^\circ\text{C}$ , using  $\leq 10\text{s}$  junction-to-ambient thermal resistance.
- c. The value of  $R_{\theta_{JA}}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ . The value in any given application depends on the user's specific board design.
- d. The  $R_{\theta_{JA}}$  is the sum of the thermal impedance from junction to lead  $R_{\theta_{JL}}$  and lead to ambient.